



**2007 KGD Packaging & Test Workshop**  
 September 9-12, 2007 Embassy Suites, Napa, CA

James Adams	3M	USA
Mike Farrell	3M	USA
Martin Hemmerling	Aehr Test Systems	USA
Rhea Posedel	Aehr Test Systems	USA
Chuck Lhota	Air Products & Chemicals, Inc.	USA
Jim Repko	AJ Industries	USA
Sergey Savastiouk	Allvia	USA
Shin Yoshida	ALPS Electric Co, LTD	Japan
Daisuke Takai	ALPS Electric (North America) Inc.	USA
Bob Doherty	Analog Devices	USA
Chiu-Feng Chang	King Yuan Electronics Corporation	Taiwan
James Farley	Analog Devices	USA
Tom Grein	Analog Devices	USA
James Zhou	Antares Advanced Test Technologies	USA
Mark Murdza	Antares Advanced Test Technologies	USA
Mali Venkatesan	Applied Materials	USA
Andrew Snow	Applied Precision	USA
Calvin Cheung	ASE	USA
CP Hung	ASE	R.O.C.
Jenny Chang	ASE	USA
Mike Kondrat	Cascade MicroTech	USA
Russ Schlager	Cascade Microtech	USA
Roger Hayward	Cascade Microtech, Inc.	USA
Gene Selven	Chip Scale Review	USA
Kim Newman	Chip Scale Review	USA
Jim Rates	Chip Supply, Inc.	USA
Jim Wolbert	Chip Supply, Inc	USA
Ching-Too Chen	Chroma ATE	USA
Eddie Bromilow	ClearSpeed Technology plc	U.K.
Marla Cooper	Cooper Consulting Services, Inc	USA
Greg May	Delphi Corporation	USA
Jeanne Beacham	Delphon Industries	USA
Larry Gilg	Die Products Consortium	USA
Stefano Saggini	Dipartimento di Ingegneria Elettrica Gestionale e Meccanica Universita' di Udine	ITALY
Philip Garrou	Dow Chemical Co.	USA
Ryoji Maruyama	Enplas Semiconductor Peripheral Corp.	Japan
Jesse Reuter	Enplas Tesco Inc.	USA
Harald Ibele	ERS America LLC	USA
Stephen Fossi	Formfactor	USA
Ben Eldridge	FormFactor, Inc.	USA
Dane Granicher	FormFactor, Inc.	USA
David Polityko	Fraunhofer IZM	Germany
Stephan Guttowski	Fraunhofer IZM	Germany
Michael (Jeff) Bosworth	Freescale Semiconductor Inc.	USA
Takashi Sato	FROM30 Co Ltd	USA



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David Keezer	Georgia Institute of Technology	USA
Tetsuya Onishi	Grand Joint Technology Ltd.	Hong Kong
Jody Van Horn	IBM	USA
Carl Smets	ICOS Vision Systems	Belgium
Darin Pizzo	ICOS Vision Systems	USA
Pieter Vandewalle	ICOS Vision Systems	Be
Bob Fusco	Inapac	USA
Chiate Lin	Inapac Technology, Inc.	USA
Franco Mariana	Infineon	Germany
Georg Meyer-Berg	Infineon Technologies	Germany
Peter Ossimitz	Infineon Technologies	Germany
Peter Muhmenthaler	Infineon Technologies AG	Germany
Brian Bradford	Intel	USA
Eric J.M. Moret	Intel Corp	USA
Ken Teasdale	International Rectifier	USA
Bob Giovannetti	Ismecca, USA	USA
Thomas Soulliere	Ismecca, USA	USA
Ken Ball	KBTec	UK
Dave Huntley	Kinesys Software	USA
Wendy Chen	King Yuan Electronics Co., Ltd	R.O.C
Yuji Kimura	Kogakuin University	Japan
HC Peng	KYEC USA	USA
Chun-Yen Kuo	Macronix International Co. Ltd	Taiwan
Hung Cheng Tu	Macronix International Co. Ltd	Taiwan
Gary Castleman	Marvell	USA
Mohsen Askarinya	Medtronic	USA
Reynaud Vincent	Mesatronic	France
John Persic	Microbonds Inc	USA
Robert Lyn	Microbonds Inc	USA
Tony Hallan	Micron	US
Jennifer Cheffings	Micron Technology	USA
Lee Nevill	Micron Technology, Inc.	USA
Michael Fink	Mindspeed Semiconductor	USA
Marcos Karnezos	MK Consulting	USA
Gerald Steinwasser	Mühlbauer	USA
Bill Bottoms	Nanonexus	USA
Bill Price	NXP	USA
Christophe Kelma	NXP	France
Frans de Jong	NXP	The Netherlands
Mike Marks	PacTech USA	USA
Thorsten Teutsch	PacTech USA	USA
Gene Dunn	Panasonic FA	United States
Takatoshi Ishikawa	Panasonic Factory Solutions	Japan
Katrina Frazer	PenWell Corporation	USA
Arun Amirtham	Philips Semiconductors	Switzerland
Jinyong Chung	POSTECH	Korea



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Kenneth Lafenhagen	PVA TePla America	USA
Patrick Haibach	Qimonda	Germany
Peng Lin	Qualcomm	USA
Hoang Nguyen	Qualcomm, Inc.	USA
Michael Campbell	Qualcomm, Inc	USA
Octavio Martinez	Qualcomm, Inc.	USA
John Groat	Ramtron International Corporation	USA
Sejang Oh	Samsung Electronics	Korea
Young Dae Kim	Samsung Electronics	Korea
Jeff Hintzke	Scanimetrics	USA
Clayton Householder	Scanimetrics	Canada
Dan Cormack	Semi Dice, Inc.	USA
Laura Margeson	Semi Dice, Inc.	USA
Don Feuerstein	SemiProbe	USA
Masahiro Kyojuka	Shinko Electric America	USA
Rick McDonald	Shinko Electric America	USA
Gary Lawman	Silicon Blue Tech	USA
John Birkner	Silicon Blue Tech	USA
Kapil Shankar	Silicon Blue Tech	USA
Mark McMeen	Soldering Technology	USA
Ryoji Hagiwara	Sony	Japan
Fely Krewell	Spansion	USA
Jin Zhu	Spansion	USA
Mike Costello	Star Lab, Inc.	USA
Wong Kok Sun	STATS ChipPAC	Singapore
Casey Cooper	STI Electronics	USA
Roberto Canegallo	STMicroelectronics	Italy
Becky Travelstead	TechSearch International	USA
Jan Vardaman	TechSearch International, Inc.	USA
Charles Gutentag	Tempo Electronics	USA
Ken Harvey	Teradyne	USA
Yoichi Kubota	Tessera, Inc.	USA
Doyce Ramey	Texas Instruments	USA
Andrey Veitsel	Topcon Positioning Systems	USA
Arseny Chugunkin	Topcon Positioning Systems	USA
Igor Orlovsky	Topcon Positioning Systems	USA
Maxim Abramov	Topcon Positioning Systems	USA
Pavel Ivanov	Topcon Positioning Systems	USA
Norihiro Togasaki	Toshiba Corp.	Japan
Heather Karklin	Touchdown Technologies	USA
Earl Sausen	True Integration	USA
John Liobe	UMASS Lowell	USA
Gavin Chan	Universal Enterprise	Hong Kong
Ling Chan	Universal Enterprise	Hong Kong
Martin Margala	University of Massachusetts Lowell	USA
Robert Schneider	Verigy	USA